2SC4559

Silicon NPN triple diffusion planar type

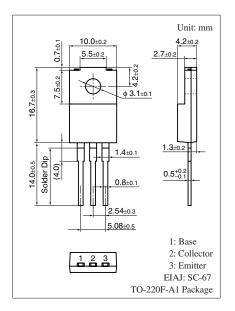
For high breakdown voltage high-speed switching

■ Features

- High-speed switching
- ullet High collector-emitter voltage (Base open) V_{CEO}
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_C = 25$ °C

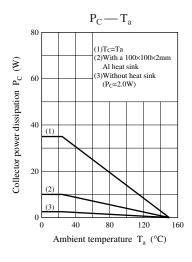
| Parameter | Symbol | Rating | Unit | |
|---------------------------------------|------------------|-------------|------|--|
| Collector-base voltage (Emitter open) | V _{CBO} | 500 | V | |
| Collector-emitter voltage (E-B short) | V _{CES} | 500 | V | |
| Collector-emitter voltage (Base open) | V _{CEO} | 400 | V | |
| Emitter-base voltage (Collector open) | V_{EBO} | 7 | V | |
| Base current | I_B | 3 | A | |
| Collector current | I_C | 7 | A | |
| Peak collector current | I_{CP} | 15 | A | |
| Collector power dissipation | P _C | 35 | W | |
| $T_a = 25^{\circ}C$ | | 2.0 | | |
| Junction temperature | T_{j} | 150 | °C | |
| Storage temperature | T _{stg} | -55 to +150 | °C | |

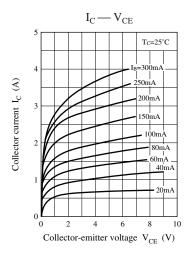


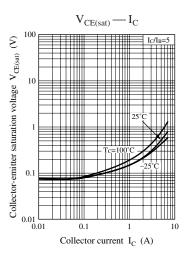
■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

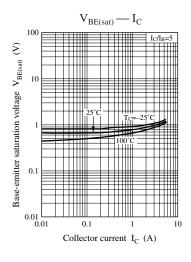
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|--|----------------------|---|-----|-----|-----|------|
| Collector-emitter voltage (Base open) | V _{CEO} | $I_C = 10 \text{ mA}, I_B = 0$ | 400 | | | V |
| Collector-base cutoff current (Emitter open) | I_{CBO} | $V_{CB} = 500 \text{ V}, I_E = 0$ | | | 100 | μΑ |
| Emitter-base cutoff current (Collector open) | I_{EBO} | $V_{EB} = 5 \text{ V}, I_{C} = 0$ | | | 100 | μΑ |
| Forward current transfer ratio | h _{FE1} | $V_{CE} = 5 \text{ V}, I_{C} = 0.1 \text{ A}$ | 10 | | | _ |
| | h _{FE2} | $V_{CE} = 5 \text{ V}, I_{C} = 3 \text{ A}$ | 8 | | | |
| Collector-emitter saturation voltage | V _{CE(sat)} | $I_C = 3 \text{ A}, I_B = 0.6 \text{ A}$ | | | 1.0 | V |
| Base-emitter saturation voltage | V _{BE(sat)} | $I_C = 3 \text{ A}, I_B = 0.6 \text{ A}$ | | | 1.5 | V |
| Transition frequency | f_T | $V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 1 \text{ MHz}$ | | 10 | | MHz |
| Turn-on time | t _{on} | $I_C = 3 A$ | | | 1.0 | μs |
| Storage time | t _{stg} | $I_{B1} = 0.6 \text{ A}, I_{B2} = -1.2 \text{ A}$ | | | 2.0 | μs |
| Fall time | t _f | $V_{CC} = 150 \text{ V}$ | | | 0.3 | μs |

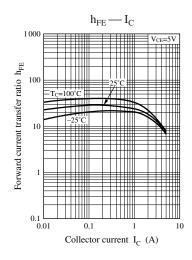
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

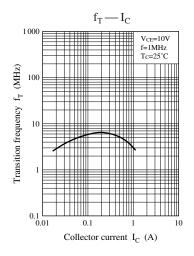


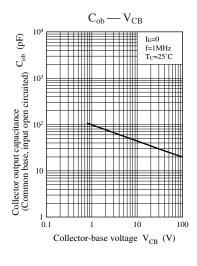


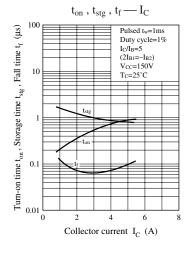


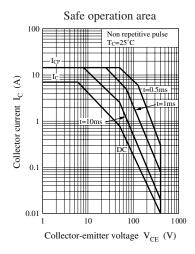




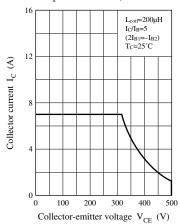




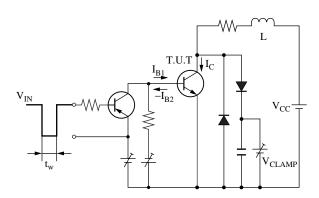


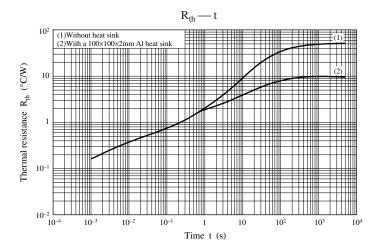


Safe operation area (Reverse bias)



Safe operation area (Reverse bias) measurement circuit





SJD00131BED 3

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